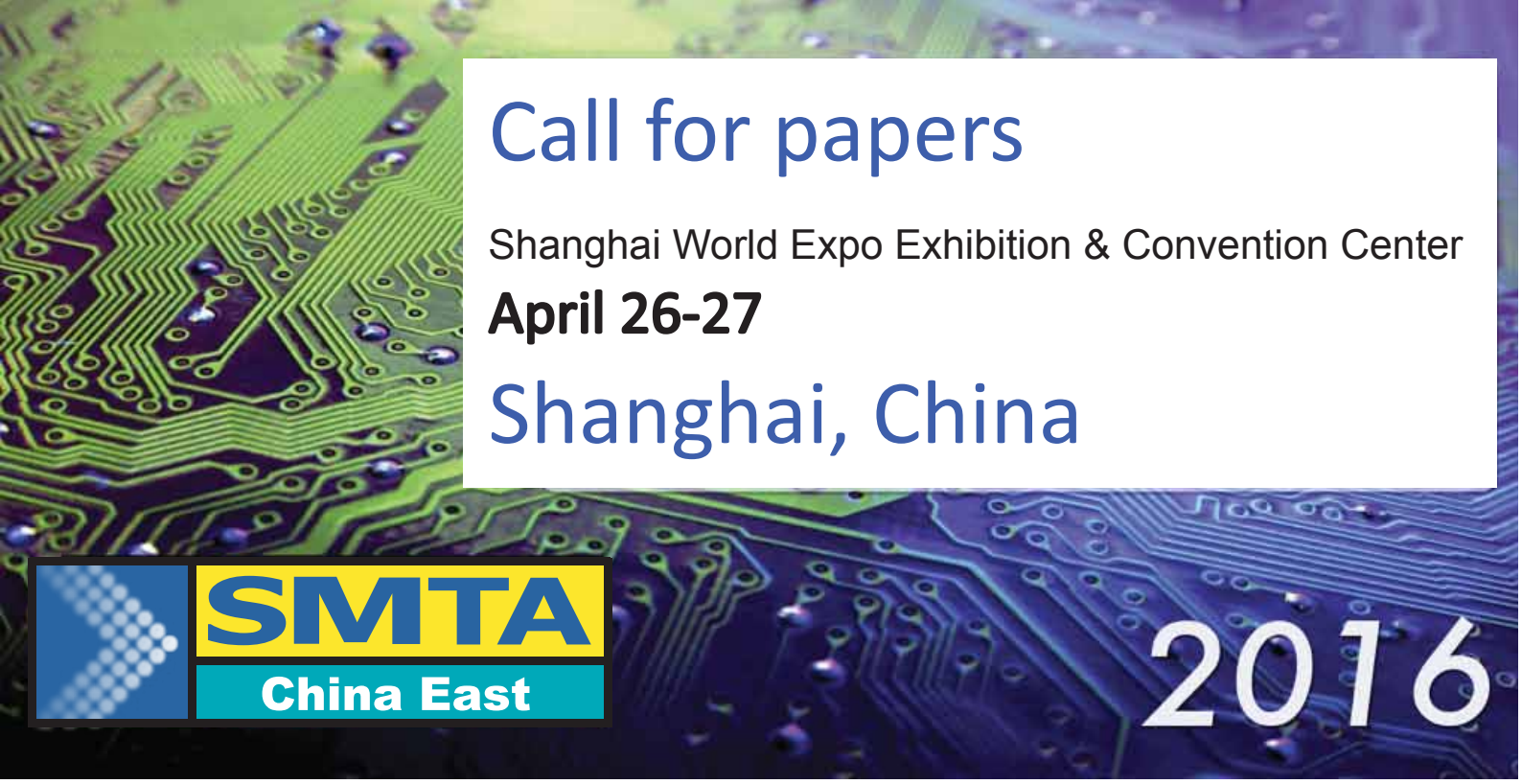

FOR IMMEDIATE RELEASE

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Greetings to our Valued SMTA Speakers and Industry Colleagues

SMTA China East

In conjunction with

THE 26TH PRESENTATION NEPCON MICROELECTRONICS CHINA 2016
第二十六届中国国际电子生产设备暨微电子工业展

Call for Papers 2016 for the Technology Conference

The SMTA China cordially invites you to participate in SMTA China East Conference located in Shanghai 2016. This event, held in conjunction with NEPCON China 2016, will as usual address the industry's most pressing issues in Advanced Packaging/Components, Assembly, Business/Supply Chain, Emerging Technologies, Harsh Environment Applications (Military, Aerospace, Automotive, Industrial, Oil & Gas), PCB Technology and Process Control .

You are invited to submit a paper to the electronic industry's premier forum on the manufacture of electronic products utilizing surface mount and related technologies. Papers are sought in the following key technology tracks:

Advanced Packaging/Components

2.5/3D Packaging and Integration
BGA/CSP
Biomedical Packaging
Component Storage
Connector Technology
Copper Pillars
Copper Wire Bonding
Diffusion Bonding
Embedded and Miniature Passives
Environmental Testing
Failure Analysis Techniques
Flip Chip
High Temperature Packaging
Lead Finishes
Magnetic Soldering
MEMS and Sensors
Moisture Sensitive Devices (MSD)
Package on Package (PoP)
Photonics
Photovoltaics and Solar
Reliability
Silver Wire-bonding
Stacked Die
System in Package (SiP)
Through Silicon Vias (TSVs)
Tin Whiskers
Wafer Level Packaging (WLP)

Assembly

01005/03015 Components/Assembly
3D Board Assembly
Additive Manufacturing
SMT Adhesives
Alternate Solder Alloys
BGA/CSP Assembly
Bottom Terminated Components
Cavity Board Assembly
Cleaning, Conformal Coating and Potting
Connector Assembly to PCB
DFX/Design for Six Sigma
Direct Chip Attach to PCB (DCA)
Dispensing & Underfill
Epoxy Fluxes
Facility Layout
Halogen and Halogen-Free
Head on Pillow Defect/Warpage
Induced Solder Joint Defects
High Melting Point Solder
Laser Soldering
Leadless Area Array Packages
Lead-Free Soldering/Reliability
Low Temperature Processing
Low Volume/Prototype
Non-Wet Open (NWO) Defects
Package-on-Package Assembly
Part Obsolescence
Placement
Printing
Reflow Soldering/ Wave Soldering
Rework and Repair of QFNs (01005, Leadless Components, PoP, Rework
Reliability
Robotic Soldering
Selective Soldering
Solder Jetting
Solder Paste/Solder Voids in Joints
Solderless Interconnections
Supplier Engineering
Thermo Compression Bonding
Underfill/ Corner Glue/ Other Polymeric Reinforcements
Vapor Phase Reflow
Yield Improvement

Business/Supply Chain

Capacity Modeling
Conflict Minerals
Contract Manufacturing
Counterfeit Parts

Doing Business in Overseas
Environmental Issues
Lean Manufacturing
Onshoring
Operations Management
Part Obsolescence
RoHS/REACH Compliance
Supplier Management
Technology Roadmaps

Emerging Technologies

<= 0.3mm Pitch Area Array Technologies
3D Circuits
3D Printing & Design Rules
Advanced Packaging
Assembly to Flex Substrates
Assembly to Glass Substrates
Cavity Assembly
Consumer Applications
Embedded Active Technology
Embedded Passive Technology
Flexible Electronics
Jetting of Solder Pastes
LED Technology/Assembly/Reliability
MEMS/RF/MOEMS
Microsystems Packaging / Modular Microsystems
Nanomaterials
Nanotechnology, Materials, & Electronics
New Materials and Processes
Optoelectronics
Plastic 3D PCB to PCB Technology
Power or Thermal Management
Power Electronics
Printed Electronics Technology
Reliability of Nanodevices
Resin Reinforcement Solder Pastes
Sensors and Manufacturing
Smart Manufacturing Systems
Small Die Size Singulation
Solid State Lighting
Solar Technology
System in a Package
Thermal Interface Materials
Touch Screen Technologies
Virtual Prototyping
Wearable Electronics
Wireless Applications

Harsh Environment Applications (Military, Aerospace, Automotive, Industrial, Oil & Gas)

Alternate Energy
Battery Prognostics
Components and Reliability
Copper Corrosion
COTS
High Lead Solder Replacement
High Temperature Electronics
Lead-free Issues
Non-Destructive Inspection
Micro-Computed Tomography
Multiphysics Modeling
Substrates and Finishes
Thermal Management
Tin Whiskers

PCB Technology

Bio-Compatible Substrates
Black Pad and Surface Finish Defects
Conductive Anodic Filament (CAF)
Creep Corrosion
Embedded Passive/Active Components
Halogen Free
HDI
High Power PCBs
Micro-vias (including filled/unfilled)
Moisture Sensitivity
New Laminate Materials
New Surface Finishes & Solderability
Pad Cratering
Soldermask
Substrate Reliability

Process Control

Acoustic Imaging (C-SAM)
Benefits of AOI & SPI
CIM
In-Circuit Test
Process Modeling
Software
Test Strategies
2D/3D X-Ray

SMTA China solicits technical papers for presentation in the **Technology Conference.** Inclusion in the Technology Conference requires strictly technical papers (**complimentary presentation slot for speakers**) subject to final acceptance by the Technical Advisory Committee of SMTA China. All papers including abstract and biography for inclusion in the Conference Proceedings **requested in both Chinese and English. All papers (powerpoint) must be in Chinese and shall be presented in Chinese or English with translator.**

SMTA CHINA	**SMTA China East** (NEPCON China)
Technology Conference 30 minutes pure technical papers presented 5 minutes for answering the question	**26-27 April 2016**

If you or your company wishes to share pertinent information with the highly qualified audience of SMTA China please submit your abstract to Peggy Chen by email to peggychen@smta.org.cn Please include your name, job title, company affiliation, and all pertinent contact information as well as your choice of Technology Conference for your paper.

Deadlines of Materials Submission for the SMTA China East Conference:

Abstract and Speaker Bio (Chinese and English version)	18 December 2015
Chinese & English version of Paper and Chinese version of PPT	29 February 2016

In order to appreciate the speakers of excellent information sharing, SMTA China would like to honor the best paper, and the speaker of best presentation, which award will be presented during the Annual Award Presentation which will be held at the venue of vendor conference in the afternnon of 26 April in Shanghai

Thank you for your support of SMTA China and we look forward to hearing from you.
Contact and Enquiry: Ms. Peggy Chen, Executive Administrator of SMTA China, Tel:+86-21-5609-3010, Fax:+86-21-5609-3020, E-mail:peggychen@smta.org.cn

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尊敬的表面装贴技术协会演讲者和业内同行

SMTA China East

同期举行于:

THE 26TH PRESENTATION NEPCON MICROELECTRONICS CHINA 2016
第二十六届中国国际电子生产设备暨微电子工业展

为高科技技术研讨会2016征集论文

中国SMTA诚意的邀请您参加2016年在上海举办的SMTA华东高科技会议。此次会议将与第二十六届中国国际电子生产设备暨微电子工业展联合举办，此次会议将涉及行业中最热门的话题，包括先进封装及元件，装配，商业与供应链，新兴技术，环保应用(军工、航天、汽车、工业、石油天然气)，基板技术和制程控制。

征集电子制造表面装贴技术及科技方面的论文，论文题材涵盖以下关键技术：

先进封装及元件

2.5/3D封装和集成
BGA/CSP
生物技术封装
元件存储
连接器技术
铜柱
铜线打线
扩散打线
嵌入及微型被动元件
环境测试
故障分析技术
倒装芯片
耐高温封装
引脚处理
磁力焊接
微型机电系统及传感器
湿度敏感器件
封装堆叠(PoP)
光子学
光伏太阳能
可靠性
银线打线
裸芯片堆叠
系统级封装
穿透硅通孔
锡须
晶圆级封装

装配

01005/03015元件及装配
3D装配
增材制造
SMT粘胶
替代焊料合金
BGA/CSP装配
底部端子元件
空腔基板装配
清洗、敷型涂覆及注胶
基板联接装配
DFX和零缺陷设计
基板上芯片直装
点胶与底部填充胶
环氧树脂助焊剂
工厂设施布置
无卤与零卤素
头枕缺陷、翘曲相关锡点缺陷
高熔点焊料
激光焊接
无引脚阵平面列封装
无铅焊接及可靠性
低温焊接
小批量与原型机
无润湿空焊
封装堆叠装配
器件废除
贴装
印刷
回流焊接与波峰焊接
精密复杂器件返修可靠性
机器人焊接
选择性焊接
喷涂式点锡膏
焊锡膏与焊点空洞
非焊接式互联
供应工程
热压打线
底部填充、边角固定及聚合物强化
汽相焊接
良率改善

商业与供应链

产能模型
冲突矿产
合同制造
高仿器件
海外业务
环境问题
精益制造
在岸外包
营运管理
器件废除

RoHS/REACH合规
供应商管理
技术路线图

新兴技术

<=0.3mm间距平面阵列技术
3D 电路
3D打印和设计规范
先进封装
柔性板装配
玻璃板装配
空腔板装配
消费电子
嵌入式主动技术
嵌入式被动技术
柔性电子
焊锡膏喷涂
LED技术、装配和可靠性
微机电系统、微光机电系统及射频技术
微系统封装、微系统模组
纳米材料
纳米技术、材料和电子
新材料与制程
光电技术
塑料3D基板联接
功耗和散热管理
电源电子
印刷电子技术
纳米器件的可靠性
助焊剂增强型锡膏
传感器与制造
智能制造系统
小型芯片切单
固体照明
太阳能技术
系统级封装
热介质材料
触摸屏技术
虚拟原型机
可穿戴电子
无线电器

环保应用(军工、航天、汽车、工业、石油天然气)

替代能源
电池剩余电量估算
元件与可靠性
铜腐蚀
COTS
高铅焊料替代
耐高温电子
无铅问题
非破坏性检查
微断层造影技术
多物理场耦合分析模型
基材与表面处理
散热管理
锡须

基板技术

生物相容基材
黑焊盘和表面处理缺陷
导电阳极丝 (CAF)
爬行腐蚀
嵌入式被动、主动元件
无卤
高密度集成HDI
高功率基板
微通孔(包括填充与非填充)
湿度敏感器件
新型层压板材料
新型表面处理和可靠性
焊盘坑裂
阻焊膜
基材可靠性

制程控制

声学成像(C-SAM)
自动光学检查的效益
计算机集成制造(CIM)
ICT在线测试
工艺制程模型
软件
测试策略
2D/3D X光检查

中国SMTA为华东高科技技术研讨会中的演讲征集技术论文。华东高科技技术研讨会的技术论文主题及内容必须为纯技术论文，经由中国SMTA技术顾问委员会最终决定后，将被列入会议题目(高科技技术研讨会的演讲者无需缴付演讲费用)。所有论文包括文章大纲和演讲者个人简介要求中文和英文刊登在技术论文集中。所有演讲（幻灯片形式的演讲稿）必须为中文并且以中文讲解或英文讲解配备翻译。

	华东高科技技术研讨会 (第二十六届中国国际电子生产设备暨电子工业展)
高科技技术研讨会 30分钟纯技术论文演讲 5分钟现场问题回答	2016年4月26日－27日

如果您和您的公司希望与中国SMTA的会员及专业观众分享贵公司的有关信息，请发邮件提交您的文章大纲给中国SMTA行政主任陈蕙至 peggychen@smta.org.cn 并写上您的名字、工作头衔和公司的相关信息以及有关联系信息并且注明您的技术论文是投稿于高科技技术研讨会.

华东高科技技术研讨会提交材料的截至日期：

文章大纲和演讲者个人简介(中文和英文版本)　2015年12月18日
中英文版本的论文和中文的幻灯片形式的演讲稿　2016年2月29日

为了感谢演讲者们优秀信息的分享，中国SMTA将于上海4月26日下午在设备技术研讨会的演讲现场举办的周年颁奖典礼上颁发最佳论文奖和最佳演讲奖.

感谢您支持中国SMTA，期待您的消息。
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